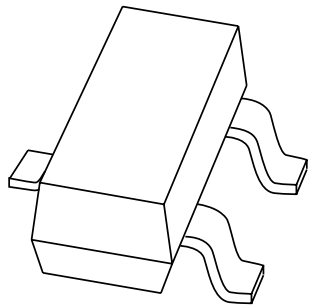


# DATA SHEET



**PBSS5130T**

30 V, 1 A

PNP low  $V_{CEsat}$  (BISS) transistor

Product specification

2003 Dec 12

## 30 V, 1 A PNP low $V_{CEsat}$ (BISS) transistor

PBSS5130T

### FEATURES

- Low collector-emitter saturation voltage  $V_{CEsat}$
- High collector current capability:  $I_C$  and  $I_{CM}$
- Higher efficiency leading to less heat generation
- Reduced printed-circuit board requirements
- Cost effective alternative to MOSFETS in specific applications.

### APPLICATIONS

- Power management
  - DC/DC converters
  - Supply line switching
  - Battery charger
  - LCD backlighting.
- Peripheral drivers
  - Driver in low supply voltage applications (e.g. lamps and LEDs)
  - Inductive load driver (e.g. relays, buzzers and motors).

### DESCRIPTION

PNP low  $V_{CEsat}$  transistor in a SOT23 plastic package.

### MARKING

TYPE NUMBER	MARKING CODE <sup>(1)</sup>
PBSS5130T	*3E

### Note

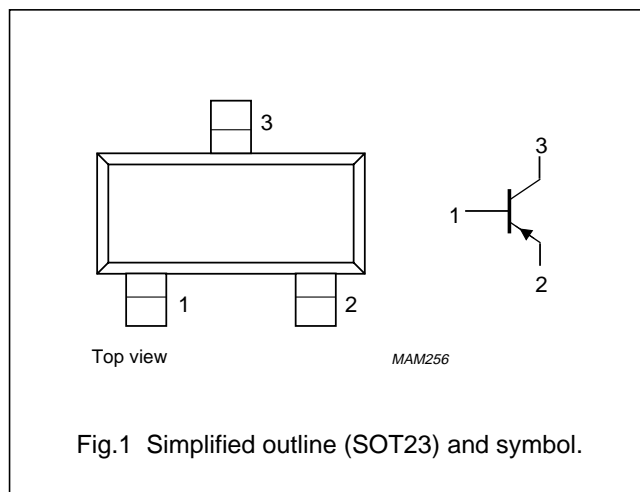
1. \* = p : made in Hong Kong  
\* = t : made in Malaysia  
\* = W : made in China.

### QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
$V_{CEO}$	collector-emitter voltage	-30	V
$I_C$	collector current (DC)	-1	A
$I_{CRP}$	repetitive peak collector current	-1.5	A
$R_{CEsat}$	equivalent on-resistance	220	m $\Omega$

### PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



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PBSS5130T

## ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
PBSS5130T	–	plastic surface mounted package; 3 leads	SOT23

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CBO}$	collector-base voltage	open emitter	–	–30	V
$V_{CEO}$	collector-emitter voltage	open base	–	–30	V
$V_{EBO}$	emitter-base voltage	open collector	–	–5	V
$I_C$	collector current (DC)		–	–1	A
$I_{CM}$	peak collector current		–	–3	A
$I_{BM}$	peak base current		–	–300	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$ note 1 note 2	– –	300 480	mW mW
$T_{stg}$	storage temperature		–65	+150	°C
$T_j$	junction temperature		–	150	°C
$T_{amb}$	operating ambient temperature		–65	+150	°C

## Notes

1. Device mounted on an FR4 printed-circuit board, single-sided copper, tinplated, standard footprint.
2. Device mounted on an FR4 printed-circuit board, single sided-copper, tinplated, mounting pad for collector 1 cm<sup>2</sup>.

## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	in free air note 1 note 2	417 260	K/W K/W

## Notes

1. Device mounted on an FR4 printed-circuit board, single-sided copper, tinplated and standard footprint.
2. Device mounted on an FR4 printed-circuit board, single-sided copper, tinplated and mounting pad for collector 1 cm<sup>2</sup>.

# 30 V, 1 A

## PNP low $V_{CEsat}$ (BISS) transistor

PBSS5130T

**CHARACTERISTICS** $T_{amb} = 25\text{ °C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_{CBO}$	collector-base cut-off current	$V_{CB} = -30\text{ V}; I_E = 0$	–	–	–100	nA
		$V_{CB} = -30\text{ V}; I_E = 0; T_j = 150\text{ °C}$	–	–	–50	$\mu\text{A}$
$I_{EBO}$	emitter-base cut-off current	$V_{EB} = -4\text{ V}; I_C = 0$	–	–	–100	nA
$h_{FE}$	DC current gain	$V_{CE} = -2\text{ V}; I_C = -100\text{ mA}$	300	450	–	
		$V_{CE} = -2\text{ V}; I_C = -500\text{ mA}$	260	350	–	
		$V_{CE} = -2\text{ V}; I_C = -1\text{ A}$	210	290	–	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = -100\text{ mA}; I_B = -1\text{ mA}$	–	–	–100	mV
		$I_C = -1\text{ A}; I_B = -50\text{ mA}$	–	–	–225	mV
$R_{CEsat}$	equivalent on-resistance	$I_C = -500\text{ mA}; I_B = -50\text{ mA};$ note 1	–	–	220	$\text{m}\Omega$
$V_{BEon}$	base-emitter turn-on voltage	$V_{CE} = -2\text{ V}; I_C = -100\text{ mA}$	–	–	–0.75	V
$f_T$	transition frequency	$I_C = -100\text{ mA}; V_{CE} = -10\text{ V};$ $f = 100\text{ MHz}$	100	200	–	MHz
$C_c$	collector capacitance	$V_{CB} = -10\text{ V}; I_E = I_e = 0; f = 1\text{ MHz}$	–	–	28	pF

**Note**

1. Pulse test:  $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$ .

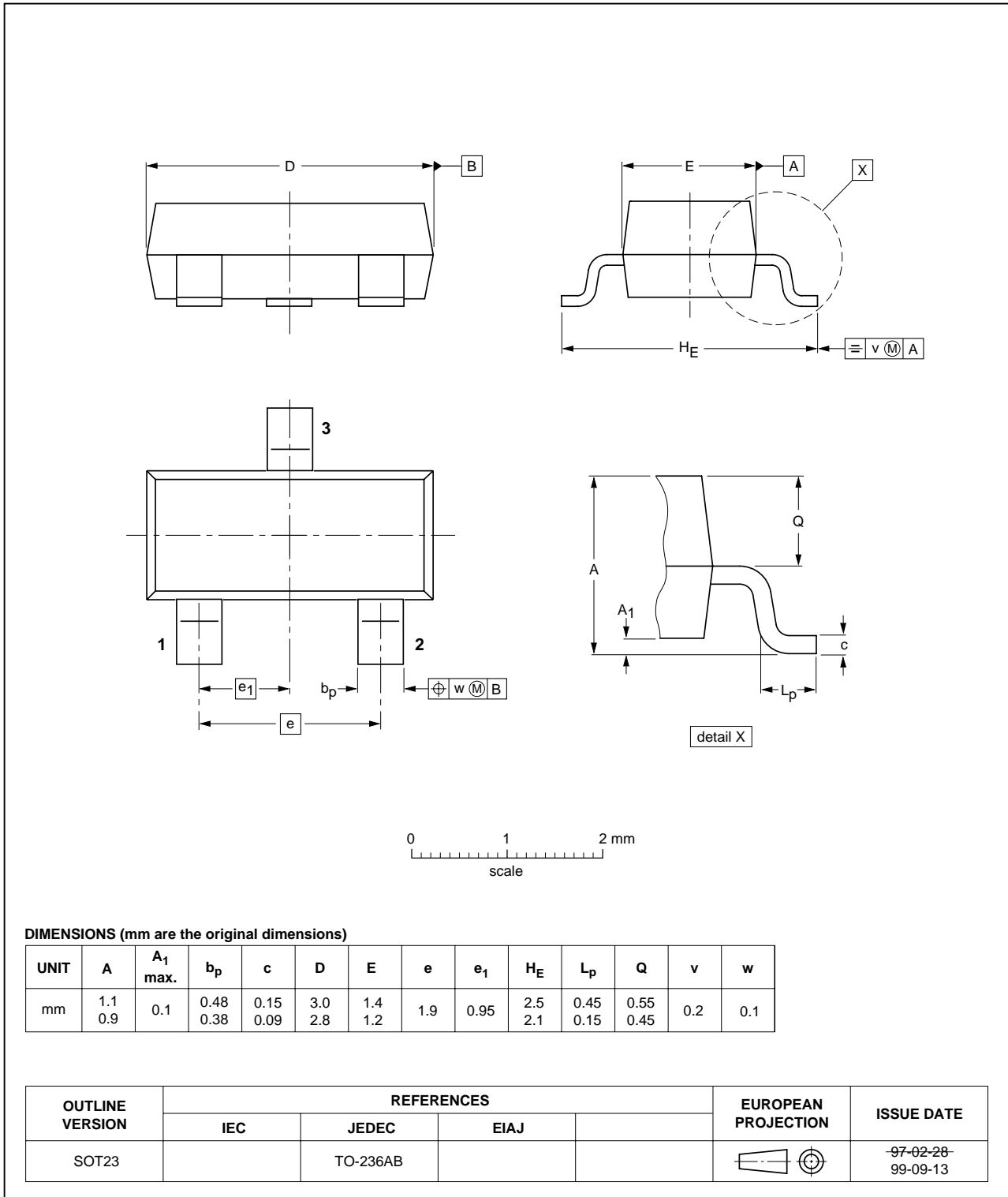
30 V, 1 A  
PNP low  $V_{CEsat}$  (BISS) transistor

PBSS5130T

PACKAGE OUTLINE

Plastic surface mounted package; 3 leads

SOT23



30 V, 1 A  
PNP low  $V_{CEsat}$  (BISS) transistor

PBSS5130T

#### DATA SHEET STATUS

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)(3)</sup>	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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**Limiting values definition** — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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